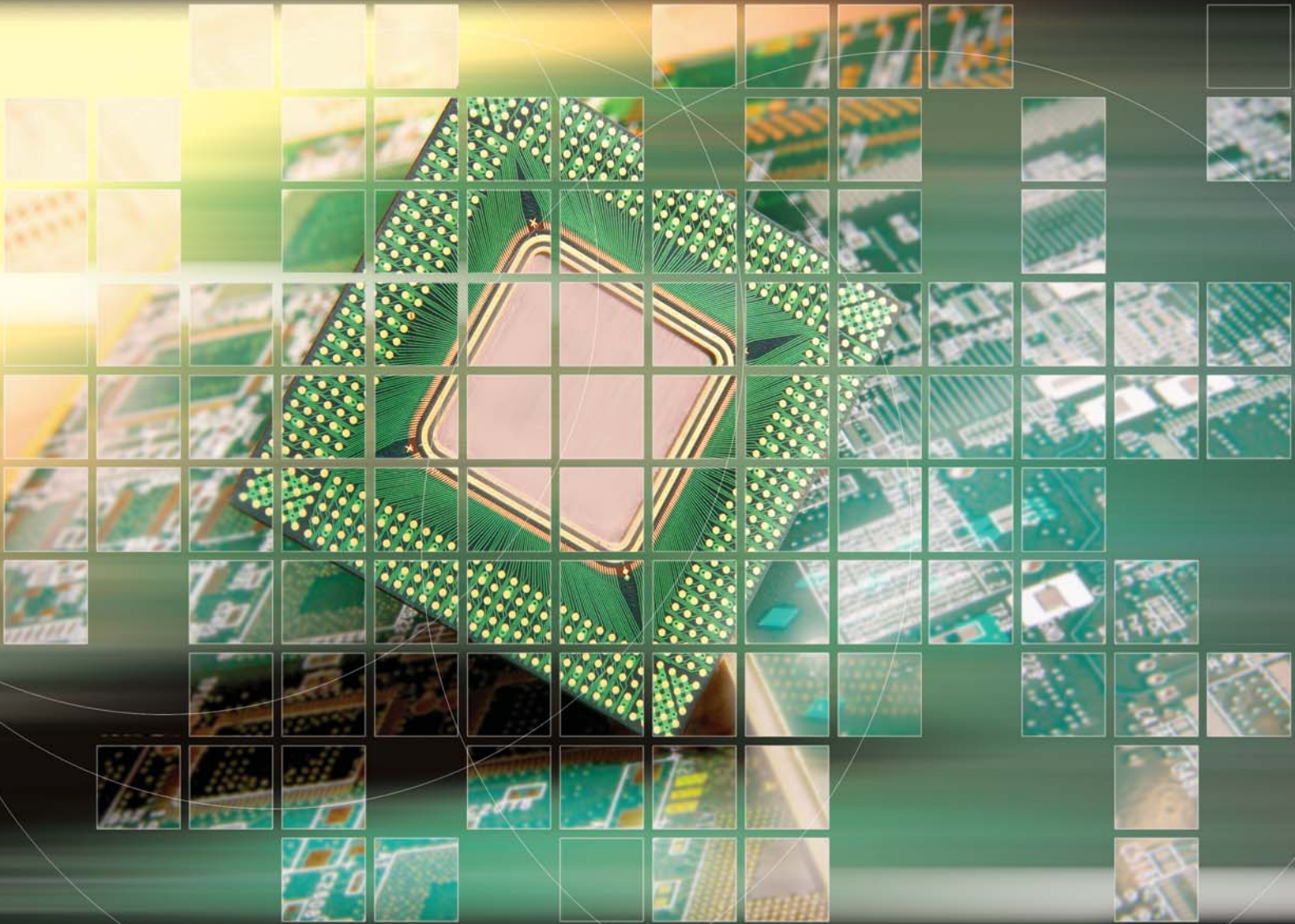


# MICROVIAS & FINE LINES

BLIND • BURIED • LASER DRILLED • 25 MICRONS



*Compunetics is one of the few PCB manufacturers in the world to make these versatile boards for specialized applications and unusual physical constraints.*

**compunetics**  
excellence, measured in microns.

*Compunetics is the vendor of choice when requirements include very high density interconnects.*

**Microvia specifications:**

- Laser microvias as small as 1 mil (25 µm)
- In-house YAG laser
- Mechanical drilled
- Stacked and stepped microvias

**Fine lines:**

Compunetics is a pioneer in very high density circuitry. Fine lines are produced using the latest generation photoresist resulting in circuits as small as 1 mil (25 µm).

Compunetics microvias and fine line circuitry is the perfect fit for applications including:

- Supercomputing
- Military
- Medical
- Telecommunications
- Chip packaging
- High density flex connectors

**Stacked Microvias**

*Sequential build: 3 layers RCC both sides.*

**Specifications**

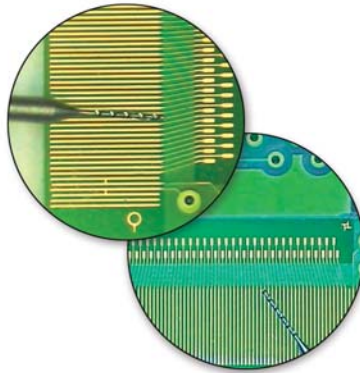
- Layers: 8  
 Trace/Space: 2/3 (50/75 µm)  
 Blind Microvias  
 Stacked Microvias  
 Sequential Build  
 3 Layers RCC top & bottom  
 Finish: Electrolytic Ni/Au



**Fine Line**

**Specifications**

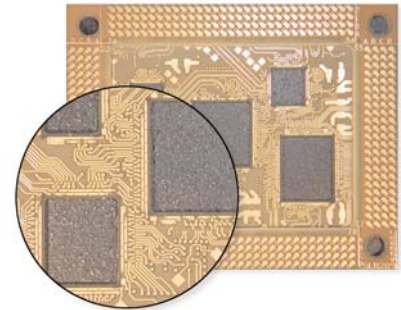
- Layers: 4  
 Trace/Space: 1.5/1.5 (35/35 µm)  
 Finish: Electrolytic Ni/Au  
 Thickness: 31 ± 1 mils



**High Layer Fine Line**

**Specifications**

- Layers: 14  
 Trace/Space: 2/2 (50/50 µm)  
 Finish: Electrolytic Gold  
 Blind Vias  
 Cavity Design  
 2 Buried Resistor Layers



**MICROVIAS**

*Stacked Microvias • Buried Microvias • Stepped Microvias • Thru Microvias*

